Master Bond EP21ND Non Drip Room Temperature Curing Epoxy System

Category : Polymer , Adhesive , Thermoset , Epoxy , Epoxy Adhesive

Material Notes:

Master Bond Polymer System EP21ND is a two component, room temperature curing epoxy adhesive featuring outstanding physical properties. EP21ND can be mixed by weight or volume and is available in a special non drip formula. Conforms Title 21, U.S. Code of Federal Regulations, FDA Chapter 1, Section 175.105 for Food Applications.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Master-Bond-EP21ND-Non-Drip-Room-Temperature-Curing-Epoxy-System.php

Thermal Properties	Metric	English	Comments	
Maximum Service Temperature, Air	121 °C	250 °F		
Minimum Service Temperature, Air	-51.1 °C	-60.0 °F		

Processing Properties	Metric	English	Comments
Cure Time	120 min	2.00 hour	
	@Temperature 93.3 °C	@Temperature 200 °F	
	1440 - 2880 min	24.0 - 48.0 hour	
@Temperature 23.0 °C		@Temperature 73.4 °F	

Descriptive Properties	Value	Comments
Color Code	"A" Gray; "B" Tan	
Mix Ratio By Weight	100/100	
Set-Up Time, minutes	45-60	At Room Temperature
Viscosity	Paste	Room Temperature

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